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Part Number: [0783150011](#)
Status: **Active**
Description: 1.00mm (.039") Pitch DDR3 DIMM Socket, Very Low Profile, Vertical, Press-Fit, with Pegs, Black Housing and Latches, 0.76µm (30µ") Gold (Au)Plating, 2.85mm (.112") Compliant Pin Length, 2.60mm (.102") PCB Thickness, 240 Circuits, Lead free

Documents:

[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Product Specification PS-78315-001 \(PDF\)](#)

General

Product Family	Memory Module Sockets
Series	78315
Component Type	Socket
JEDEC Outline	MO-269
Product Name	DDR3 DIMM

Physical

Circuits (Loaded)	240
Circuits (maximum)	240
Color - Resin	Black
Durability (mating cycles max)	25
Entry Angle	Vertical
Function Key	None
Keying to Mating Part	Yes
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	Nylon
PC Tail Length (in)	0.112 In
PC Tail Length (mm)	2.85 mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness Recommended (in)	0.102 In
PCB Thickness Recommended (mm)	2.60 mm
Packaging Type	Tray
Pitch - Mating Interface (in)	0.039 In
Pitch - Mating Interface (mm)	1.00 mm
Pitch - Term. Interface (in)	0.039 In
Pitch - Term. Interface (mm)	1.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.76
Plating min: Termination (µin)	15
Plating min: Termination (µm)	0.38
Temperature Range - Operating	-55°C to +85°C
Termination Interface: Style	Through Hole - Compliant Pin

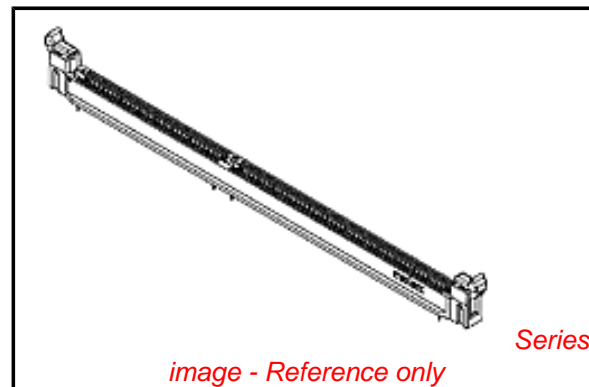
Electrical

Current - Maximum per Contact	1A
Voltage - Maximum	30V AC (RMS)/DC
Voltage Key	Center

Material Info

Reference - Drawing Numbers

Application Specification	AS-78315-001
Product Specification	PS-78315-001, RPS-78315-001



EU RoHS

**ELV and RoHS
Compliant**
**REACH SVHC
Contains SVHC: No**
Halogen-Free
**Status
Not Reviewed**

China RoHS



**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

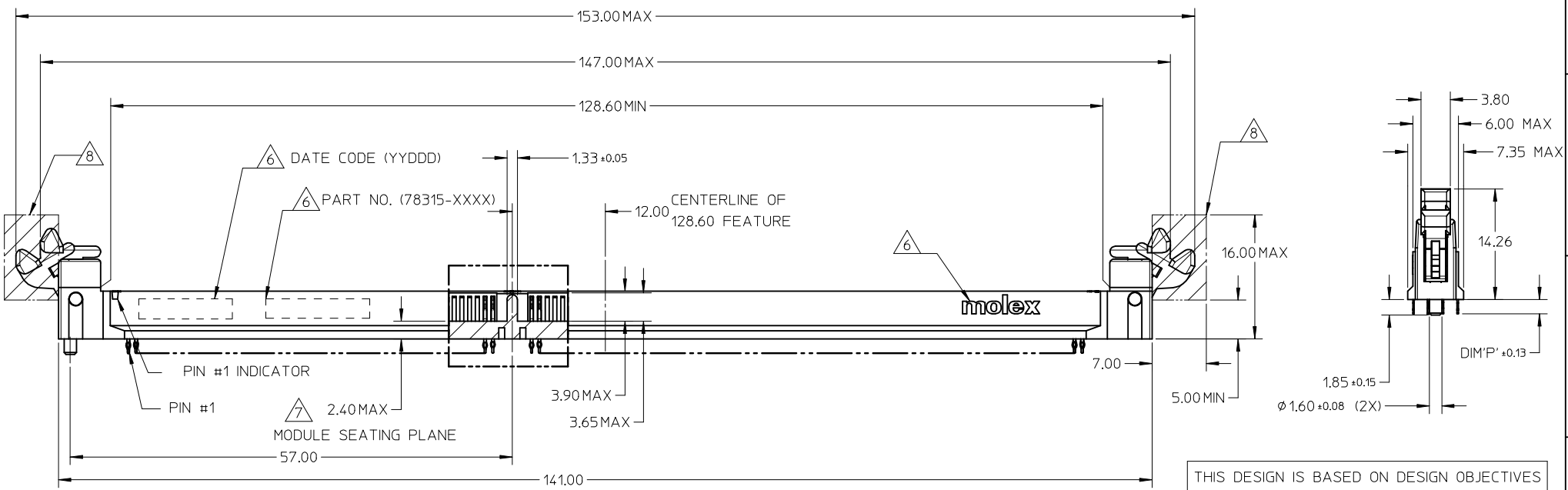
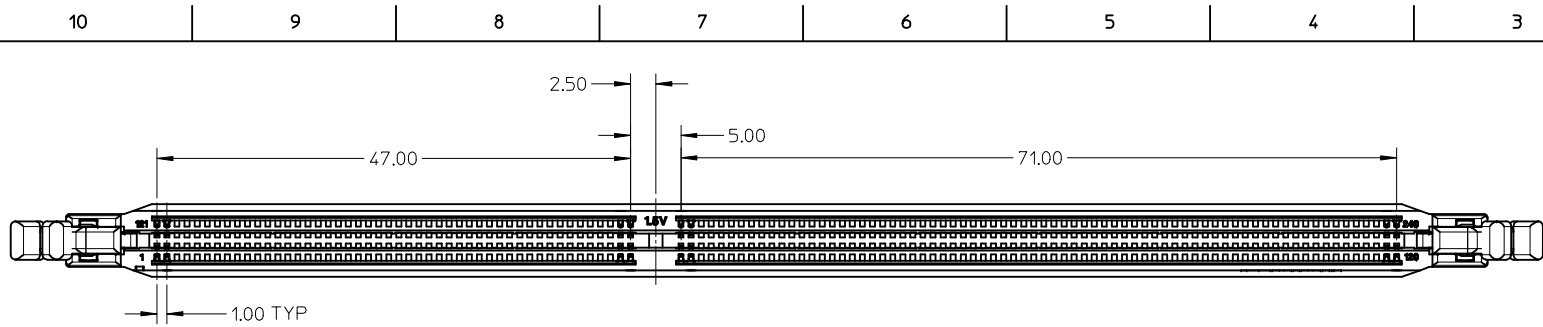
[78315Series](#)

Mates With

JEDEC standard 1.27mm modules

This document was generated on 05/17/2010

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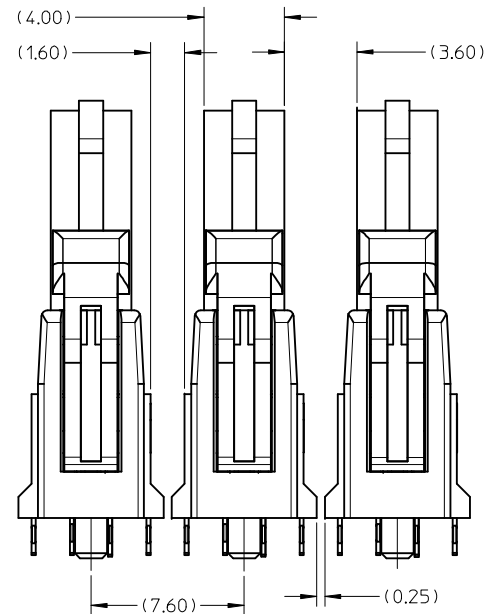
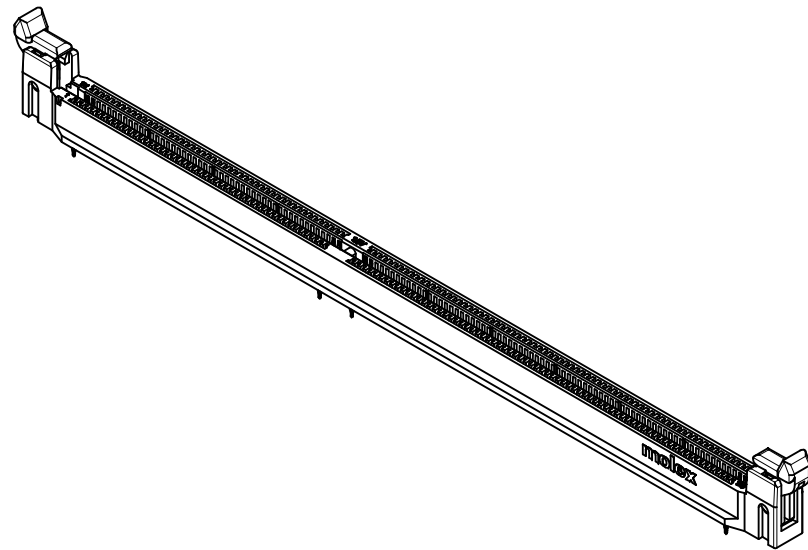
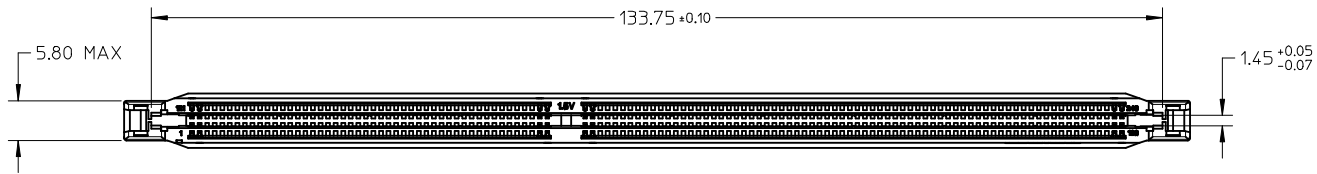


THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

- NOTES:
- MATERIAL:
HOUSING - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
LATCH - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
TERMINAL - COPPER ALLOY
 - FINISHES: TERMINAL PLATING SEE TABLE ON SHEET 5
 - PRODUCT SPECIFICATION: PS-78315-001
 - PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAYS
 - CARD SLOT ACCEPTS 1.27 +/- 0.10MM MODULE THICKNESS (MEASURED FROM PC PADS)
6. MOLEX LOGO, DATE & PART NUMBERS INDICATED ON HOUSING
7. MODULE SEATING PLANE FROM TOP OF PCB
8. KEEP OUT ZONE RESERVED FOR LATCH

ADDED OPTION EC NO: S2009-0332 DRW: CCTEH 2009/05/25 CHKD: CGTAN 2009/05/25 APPR: SHLENI 2009/05/27	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY	NTS	METRIC		
				DRAWN BY	DATE	TITLE		
				CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP)		
				CHECKED BY	DATE	1.00MM PITCH, 240 CKTS		
				CCTEH	2008/07/30	VERTICAL P/F, LOWLLCR		
				APPROVED BY	DATE	MOLEX MOLEX INCORPORATED		
				SHLENI	2008/08/01			
				MATERIAL NO.	DOCUMENT NO.	SD-78315-001	SHEET NO.	
				SEE TABLE			1 OF 6	
				SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
				A3				

10 9 8 7 6 5 4 3 2 1



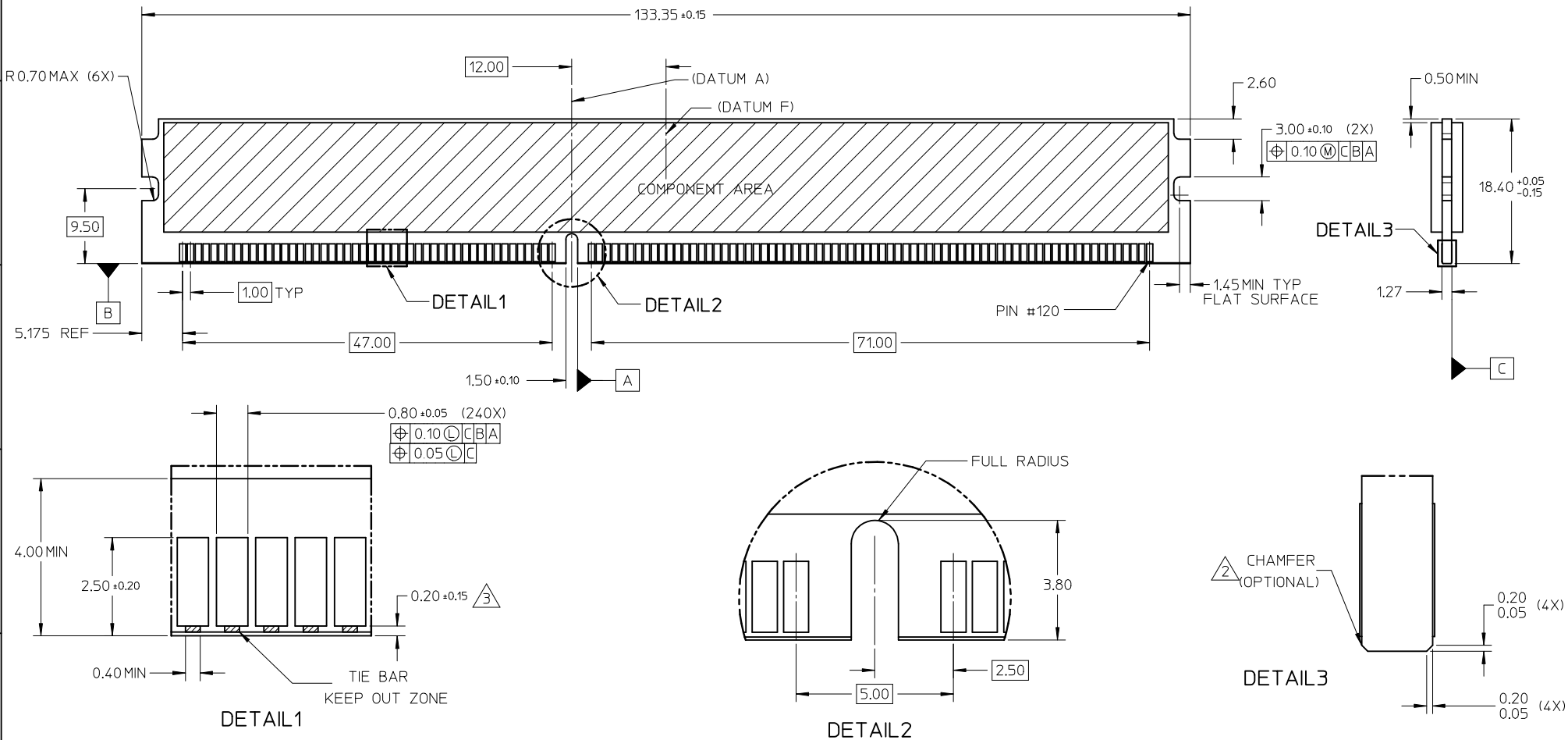
MINIMUM ROW TO ROW SPACING RECOMMENDATION
(USING 4.00MM MODULE CARD)

ADDED OPTION EC NO: S2009-0332 DRWN: CCTEH 2009/05/25 CHKD: CGTAN 2009/05/25 APPR: SHLENI 2009/05/27	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR			
		4 PLACES	± ---	± ---	CHECKED BY CCTEH	DATE 2008/07/30	MATERIAL NO. SD-78315-001			
		3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2008/08/01	DOCUMENT NO. 2 OF 6			
			2 PLACES	± 0.20	± ---	MOLEX INCORPORATED				
			1 PLACE	± ---	± ---	SEE TABLE				
			ANGULAR ± 1 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

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009MODULE CARD
 DDR3 DUAL INLINE MEMORY MODULE FAMILY 1.00 CONTACT CENTERS
 (JEDEC MO-269, ISSUE A, 12/05)



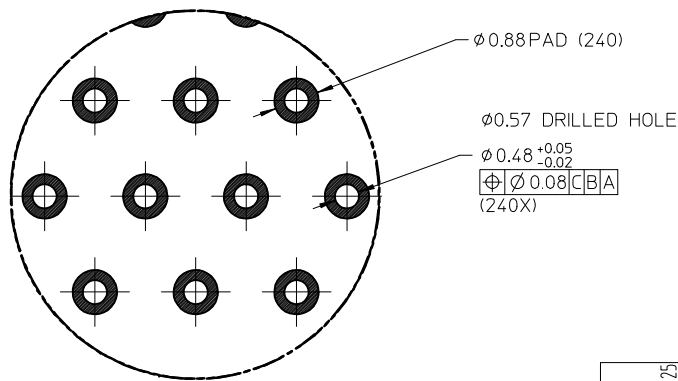
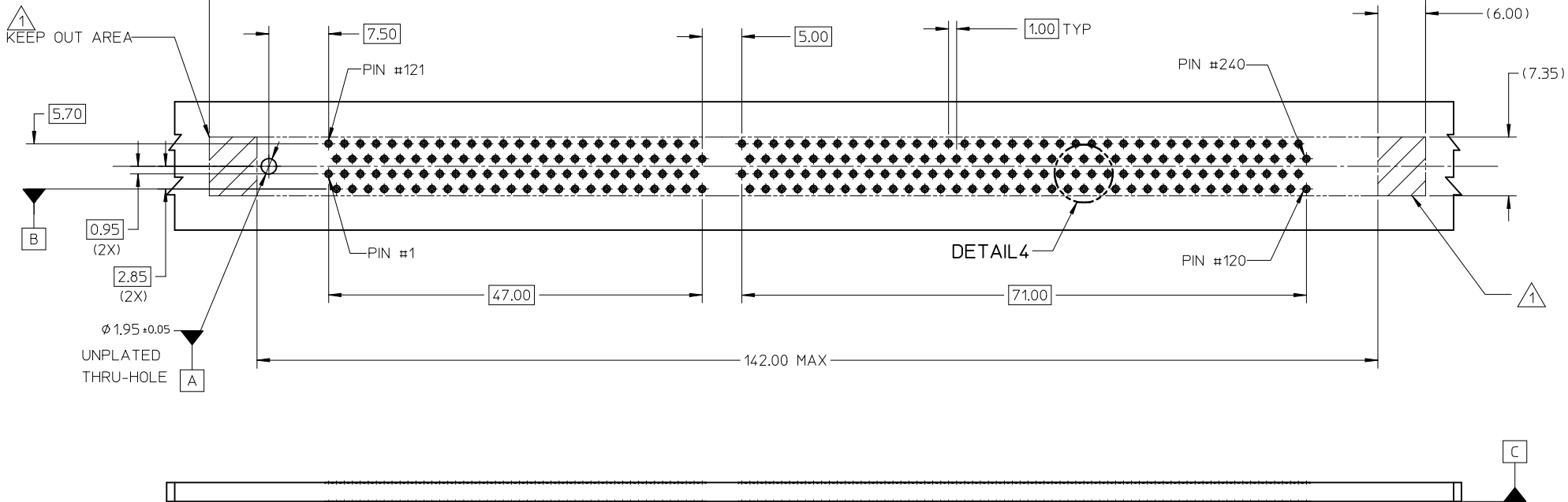
NOTES:

- RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN
 OVER 2.00 MICROMETERS NICKEL
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING
 OVER 2.00 MICROMETERS NICKEL MUST
 USE AN ELECTRONIC CONTACT GRADE
 CORROSIVE BARRIER LUBRICANT
- CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
- LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE
 SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS

ADDED OPTION EC NO: S2009-0332 DRWN: CCTEH 2009/05/25 CHKD: CGTAN 2009/05/25 APPR: SHLENI 2009/05/27	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		mm	INCH	DRAWN BY	DATE	TITLE				
		4 PLACES ± ---	± ---	CMTEO	2008/07/17	DDR3 DIMM (LSP, VLP)				
		3 PLACES ± ---	± ---	CCTEH	2008/07/30	1.00MM PITCH, 240 CKTS				
		2 PLACES ± 0.20	± ---	APPROVED BY	DATE	MOLEX INCORPORATED				
		1 PLACE ± ---	± ---	SHLENI	2008/08/01	MOLEX INCORPORATED				
		ANGULAR ± 1 °		MATERIAL NO.		DOCUMENT NO.				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-78315-001				
				SIZE	A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
						SHEET NO.				
						3 OF 6				

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10 9 8 7 6 5 4 3 2 1



DETAIL4

NOTES:

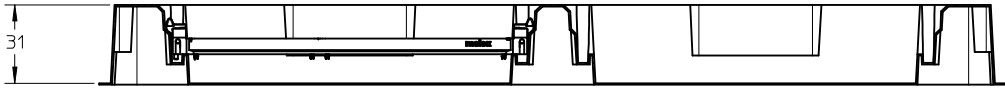
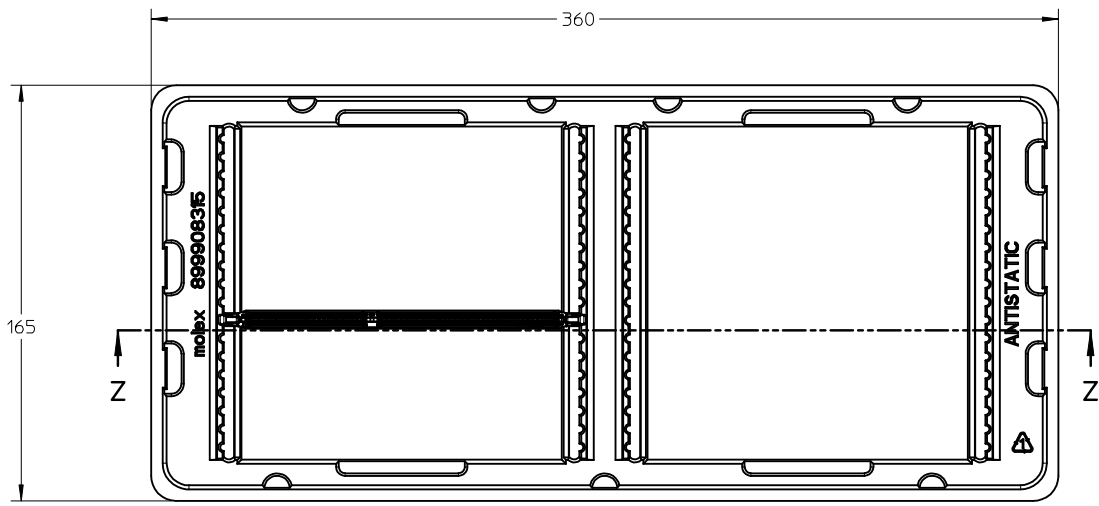
- 1. KEEP-OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB

ADDED OPTION EC NO: S2009-0332 DRWN: CCTEH 2009/05/25 CHKD: CGTAN 2009/05/25 APPR: SHLENI 2009/05/27	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION																	
			<table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.20</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.20	± ---	1 PLACE	± ---	± ---	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR			
		mm	INCH																					
	4 PLACES	± ---	± ---																					
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1 PLACE	± ---	± ---																						
		ANGULAR ± 1 °	CHECKED BY CCTEH	DATE 2008/07/30	MOLEX INCORPORATED																			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	APPROVED BY SHLENI	DATE 2008/08/01	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78315-001	SHEET NO. 4 OF 6																	

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VIEW FOR PACKAGING TRAY



SECTION Z-Z




NOTE:

1. NO. OF CAVITY - 18 X 2 =36

ADDED OPTION EC NO: S2009-0332 U DRWN: CCTEH 2009/05/25 CHKD: CGTAN 2009/05/25 APPR: SHLENI 2009/05/27	DESCRIPTION QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
				MM ONLY	NTS	METRIC			
				DRAWN BY	DATE	TITLE			
				CHECKED BY	DATE	DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR			
		APPROVED BY	DATE	MOLEX INCORPORATED					
		ANGULAR ± 1 °		SHLENI	2008/08/01	DOCUMENT NO.		SHEET NO.	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-78315-001		5 OF 6	
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				A3					

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PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	
				CONTACT AREA	TAIL AREA
78315-0001	CENTER (1.5V)	1.85	2.40	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE
78315-0201				0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN/LEAD (BRIGHT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE
78315-0011		2.85	2.60	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE

ADDED OPTION EC NO: S2009-0332 DRWN: CCTEH 2009/05/25 CHKD: CGTAN 2009/05/25 APPR: SHLENI 2009/05/27	QUALITY SYMBOLS  = 0  = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± ---	DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR				
		3 PLACES ± --- ± ---	CHECKED BY CCTEH	DATE 2008/07/30	MOLEX INCORPORATED				
		2 PLACES ± 0.20 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	APPROVED BY SHLENI	DATE 2008/08/01	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78315-001	SHEET NO. 6 OF 6		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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Наши преимущества:

- Поставка оригинальных импортных электронных компонентов напрямую с производств Америки, Европы и Азии, а так же с крупнейших складов мира;
- Широкая линейка поставок активных и пассивных импортных электронных компонентов (более 30 млн. наименований);
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
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- Поставка электронных компонентов под контролем ВП;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- При необходимости вся продукция военного и аэрокосмического назначения проходит испытания и сертификацию в лаборатории (по согласованию с заказчиком);
- Поставка специализированных компонентов военного и аэрокосмического уровня качества (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Actel, Aeroflex, Peregrine, VPT, Syfer, Eurofarad, Texas Instruments, MS Kennedy, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

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JONHON

«JONHON» (основан в 1970 г.)

Разъемы специального, военного и аэрокосмического назначения:

(Применяются в военной, авиационной, аэрокосмической, морской, железнодорожной, горно- и нефтедобывающей отраслях промышленности)

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(Применяются в телекоммуникациях гражданского и специального назначения, в средствах связи, РЛС, а так же военной, авиационной и аэрокосмической отраслях промышленности).



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